

מרכז ננו-פבריקציה

Corial DRIE 200L System





System Components:

Deep reactive Ion etcher reactor

Load lock

Laser endpoint detector

Load lock
State control switches



System operation instructions:

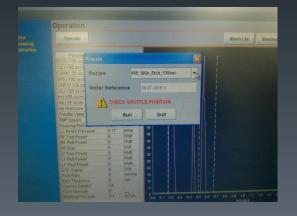
- 1. !! Insure that the roughing pump powered on. Check that the Nitrogen valve lined to the roughing pump is open. !!
- 2. If the system is in "Standby" state click "Exit".

 If the system is in "Shutdown" state click

 "Restart". System will start the TM pump and will go
 to "Vacuum Ready" state.
- 3. Press the "Vent" load lock switch. System will go to "Vent" state. Open the load lock door.
- 4. Gently placing the desired shuttle in place. Confirm that it is placed correctly. Place the substrate at the center of the shuttle.
- 5. Close the load lock door and press the "Vacuum" load lock switch. System will go to "Vacuum Ready" state. "Operate" button will appear.
- 6. Click "Operate" to start procedure.







- 7. Select the desired recipe from the list. Set the wafer reference name in the text field.
- 8. Click "Run" to start the procedure / "Quit" to cancel the operation.
- 9. End of process Click "Save process" to save and exit, "View report" to examine the process and "Quit" to exit without saving.
- 10. Press the "Vent" load lock switch. System will go to "Vent" state. Open the load lock door.
- 11. Remove the substrate.
- 12. Gently remove the shuttle and place it in the cabinet.
- 13. Close the load lock door and press the "Vacuum" load lock switch. System will go to "Vacuum Ready" state.

End of NORMAL process.

